

## Electronic Acknowledgement Receipt

<b>EFS ID:</b>	9311524
<b>Application Number:</b>	10055568
<b>International Application Number:</b>	
<b>Confirmation Number:</b>	6093
<b>Title of Invention:</b>	Chip package with die and substrate
<b>First Named Inventor/Applicant Name:</b>	Mou-Shiung Lin
<b>Customer Number:</b>	89518
<b>Filer:</b>	Dennis Alan Duchene/Patricia Balero
<b>Filer Authorized By:</b>	Dennis Alan Duchene
<b>Attorney Docket Number:</b>	085027-0059
<b>Receipt Date:</b>	26-JAN-2011
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<b>Time Stamp:</b>	15:01:51
<b>Application Type:</b>	Utility under 35 USC 111(a)

### Payment information:

Submitted with Payment	no
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### File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1		DolceralInformationDisclosureStatement-085027-0059.pdf	165549 <small>ec9e94b3ed60c3f18c167741956e10ed6e4b57dfe</small>	yes	5

	Multipart Description/PDF files in .zip description				
	Document Description		Start	End	
	Transmittal Letter		1	3	
	Information Disclosure Statement (IDS) Filed (SB/08)		4	5	
Warnings:					
Information:					
2		TS-5InformationDisclosureState ment-085027-0059.pdf	159675 <small>660a2b1b43f99803f78472c5f8a23e758a3a64</small>	yes	4
	Multipart Description/PDF files in .zip description				
	Document Description		Start	End	
	Transmittal Letter		1	2	
	Information Disclosure Statement (IDS) Filed (SB/08)		3	4	
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3		OrphanInformationDisclosureS tatement-085027-0059.pdf	185417 <small>37792552bdcfe7bdc861267b4955f7c73e392c54</small>	yes	5
	Multipart Description/PDF files in .zip description				
	Document Description		Start	End	
	Transmittal Letter		1	2	
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4	NPL Documents	1_MISTRY_45nm_logic.pdf	2254221 <small>072127b124142b6744b36305577e09475261092</small>	no	4
Warnings:					
Information:					
5	NPL Documents	2_EDELSTEIN_Advantages_of Copper.pdf	3696109 <small>d3a31204b41d4003a708a79a611a6f86250068074</small>	no	9
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6	NPL Documents	3_THENG_An_automated_tool_deployment_for_ESD.pdf	4517666 1a3d8bd7c0e154713da4fb4129e0c08eae0b34	no	7
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7	NPL Documents	4_GAO_An_improved_electrostatic_discharge_protection_structure.pdf	885848 7995c75d4f53d0c0b4e15e1853c2a9779e085	no	6
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8	NPL Documents	5_YOEH_Copper_Die_Bumps.pdf	717153 6ee072a6c3f93cd45e1d846c04bb4318ecc28a	no	5
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9	NPL Documents	6_HU_Copper_Polyimide.pdf	436455 60f3dbdc448803bc25de02121b1177bc267a05	no	7
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10	NPL Documents	7_ROESCH_Cycling_Copper_Flip_Chip_Connects.pdf	1142794 8132017f7462423c3e041aef39c245e4578ab27	no	8
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11	NPL Documents	8_LEE_Effect_of_ESD_layout_on_the_assembly_yield.pdf	889090 a7260223518155462592326de7bc38236259641d614	no	4
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12	NPL Documents	9_YEOH_ESD_effects_on_power_supply_clamps.pdf	226994 ab71bc6a5d8720a9b86ef0476e4dc5e395e0b45	no	4
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15	NPL Documents	12_JENEI_HighQInductors.pdf	279415 1749c78d4d20e8c3cc86d8748c37238ce7b831	no	3
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28	NPL Documents	25_PDF_LIN_A_New_System_ On_Chip_Technology_pdf_pdf pdf	390082 4206513aca08518b8b615872b9a151edfa 4295	no	7
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29	NPL Documents	26_PDF_MEGICA_Brochure_Lea flets_01_28_04_pdf_pdf.pdf	888383 aec894b5e67db17d13ee9632144d8fc181f 689a	no	3
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30	NPL Documents	27_PDF_LIN_Post_Passivation_ Technology_Presentation_for_ TSMC_Tech_Symposium_2003 _pdf.pdf	1277639 20556e2754a2807cc289cc5d87d24d527 17e89	no	32
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31	NPL Documents	28_PDF_LIN_A_New_IC_Interc onnection_Scheme_and_Desig n_pdf.pdf	116206 e1e1d8bb5cc0d007c7db6677a18a6a7700c eeeb8	no	4
<b>Warnings:</b>					
<b>Information:</b>					
<b>Total Files Size (in bytes):</b>			41286616		

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**New Applications Under 35 U.S.C. 111**

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

**National Stage of an International Application under 35 U.S.C. 371**

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.

**New International Application Filed with the USPTO as a Receiving Office**

If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.